



Features

Glass Passivated Die Construction Low-Forward Voltage Drop

Ideal for SMT Manufacturing Reliable Robust Construction UL Recognized File #E364304

Compact, Thin-Profile Package Design

Lead-Free Finish; RoHS Compliant (Notes 1 & 2)

contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

Halogen and Antimony Free. "Green" Device (Note 3)

For automotive applications requiring specific change control

(i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please

3A SURFACE-MOUNT LOW VF BRIDGE RECTIFIER

Product Summary

V _{RRM} (V)	I _F (A)	V _F Max (V) @ I _F = 1.5A	I _R Max (μA)	
800	3	0.88	5	

General Description

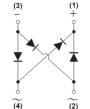
Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapters, battery chargers, home appliances, office equipment and telecommunication applications.

Mechanical Data

- Package: MSBL
- Package Material: Plastic Material, UL Flammability Classification 94V-0 (No Br. Sb, Cl)
- Moisture Sensitivity: Level 1 Per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 @3
- Polarity Indicator: Symbol Molded on Body
- Weight: 0.216 grams (Approximate)

(3) (1)





Internal Schematic

MSBL

Top View

Ordering Information (Note 4)

Orderable Part Number	Backage	Packing		
	Package	Qty.	Carrier	
MSB30L08-13	MSBL	2500pcs	Tape & Reel	

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



MB30L08 = Product Type Marking Code

Old = Manufacturer's Code Marking

YWW = Date Code Marking

Y = Last Digit of Year (ex: 5 = 2025)

WW = Week Code (01 to 53)

MSB30L08
Document number: DS45040 Rev. 3 - 2

1 of 5 www.diodes.com



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Maximum Repetitive Peak Reverse Voltage	Vrrm	800	V	
Maximum DC Blocking Voltage	VDC	800	V	
Maximum Average Rectified Output Current With Heatsink T _J = +150°C		I _{F(AV)}	3	Α
Peak Forward Surge Current 8.3ms Single Half Sine Wave Superimposed on Rated Load T _J = +25°C		IFSM	100	Α
Peak Forward Surge Current 1.0ms Single Half Sine Wave Superimposed on Rated Load T _J = +25°C		IFSM	200	Α
I ² t Rating for Fusing (t = 8.3ms)	I ² t	41.5	A ² s	
Operating Temperature Range		TJ	-55 to +150	°C
Storage Temperature Range		T _{STG}	-55 to +150	°C

Electrical Characteristics

Characteristic	Test Conditions		Symbol	Тур	Max	Unit
Forward Voltage	I _F = 1.5A	T _J = +25°C	VF	0.82	0.88	V
Leakage Current	V _R = 800V	$T_J = +25^{\circ}C$ $T_J = +125^{\circ}C$	lR	_ _	5 500	μΑ
Typical Total Junction Capacitance (Note 5)		Ст	53	_	pF	

Thermal Characteristics

Characteristic	Symbol	Тур	Unit
Typical Thermal Resistance (Without Heatsink)	Rejc Rejl Reja	9 10 76	°C/W
Typical Thermal Resistance (Note 6)	Rejc Rejl Reja	5.5 6 33	°C/W

Notes:

^{5.} Measured at 1.0MHz and applied reverse voltage of 4.0V DC. 6. Device mounted on 50mm x 50mm copper pad PCB.



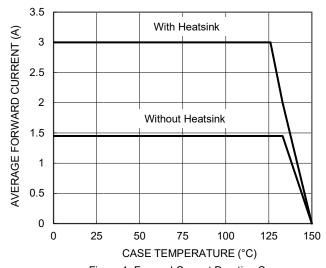


Figure 1. Forward Current Derating Curve

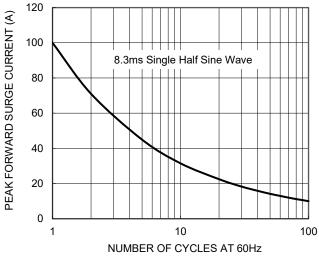
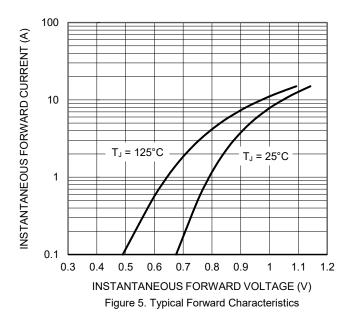


Figure 3. Maximum Non-Repetitive Surge Current



3.5 AVERAGE FORWARD CURRENT (A) With Heatsink 3 2.5 2 Without Heatsink 1.5 1 0.5 0 0 25 50 75 100 125 150 AMBIENT TEMPERATURE (°C)

Figure 2. Forward Current Derating Curve

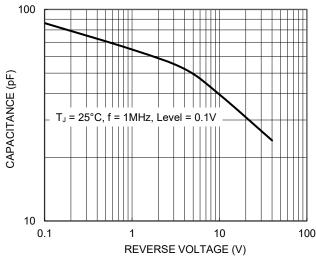


Figure 4. Typical Junction Capacitance

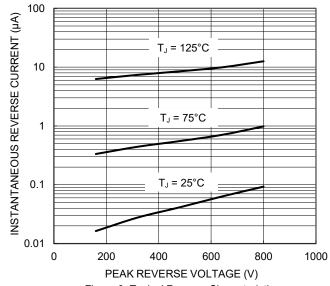


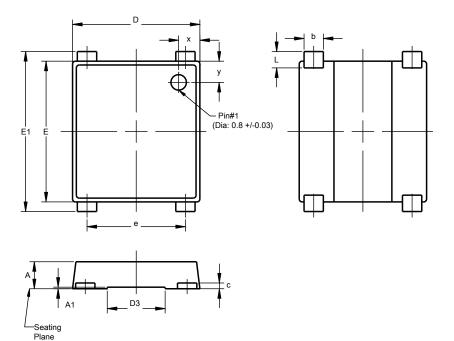
Figure 6. Typical Reverse Characteristics



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

MSBL

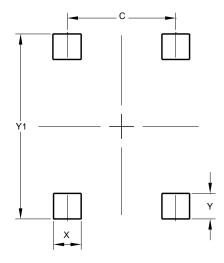


MSBL				
Dim	Min	Max	Тур	
Α	1.30	1.50	1.40	
A1	0.04	0.08	0.06	
b	0.95	1.15	1.00	
С	0.27	0.40	0.30	
D	6.50	6.70	6.60	
D3	2.90	3.10	3.00	
Е	7.20	7.40	7.30	
E1	7.90	8.60	8.30	
е	5.00	5.20	5.10	
Ĺ	0.65	1.05	0.85	
х	0.95	1.25	1.10	
у	0.95	1.25	1.10	
All Dimensions in mm				

Suggested Pad Layout

 $\label{prop:lease} Please see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

MSBL



Dimensions	Value (in mm)	
C	5.10	
X	1.30	
Y	1.20	
Y1	8.70	



IMPORTANT NOTICE

- 1. DIODES INCORPORATED (Diodes) AND ITS SUBSIDIARIES MAKE NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO ANY INFORMATION CONTAINED IN THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).
- 2. The Information contained herein is for informational purpose only and is provided only to illustrate the operation of Diodes' products described herein and application examples. Diodes does not assume any liability arising out of the application or use of this document or any product described herein. This document is intended for skilled and technically trained engineering customers and users who design with Diodes' products. Diodes' products may be used to facilitate safety-related applications; however, in all instances customers and users are responsible for (a) selecting the appropriate Diodes products for their applications, (b) evaluating the suitability of Diodes' products for their intended applications, (c) ensuring their applications, which incorporate Diodes' products, comply the applicable legal and regulatory requirements as well as safety and functional-safety related standards, and (d) ensuring they design with appropriate safeguards (including testing, validation, quality control techniques, redundancy, malfunction prevention, and appropriate treatment for aging degradation) to minimize the risks associated with their applications.
- 3. Diodes assumes no liability for any application-related information, support, assistance or feedback that may be provided by Diodes from time to time. Any customer or user of this document or products described herein will assume all risks and liabilities associated with such use, and will hold Diodes and all companies whose products are represented herein or on Diodes' websites, harmless against all damages and liabilities.
- 4. Products described herein may be covered by one or more United States, international or foreign patents and pending patent applications. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks and trademark applications. Diodes does not convey any license under any of its intellectual property rights or the rights of any third parties (including third parties whose products and services may be described in this document or on Diodes' website) under this document.
- 5. Diodes' products are provided subject to Diodes' Standard Terms and Conditions of Sale (https://www.diodes.com/about/company/terms-and-conditions/terms-and-conditions-of-sales/) or other applicable terms. This document does not alter or expand the applicable warranties provided by Diodes. Diodes does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.
- 6. Diodes' products and technology may not be used for or incorporated into any products or systems whose manufacture, use or sale is prohibited under any applicable laws and regulations. Should customers or users use Diodes' products in contravention of any applicable laws or regulations, or for any unintended or unauthorized application, customers and users will (a) be solely responsible for any damages, losses or penalties arising in connection therewith or as a result thereof, and (b) indemnify and hold Diodes and its representatives and agents harmless against any and all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim relating to any noncompliance with the applicable laws and regulations, as well as any unintended or unauthorized application.
- 7. While efforts have been made to ensure the information contained in this document is accurate, complete and current, it may contain technical inaccuracies, omissions and typographical errors. Diodes does not warrant that information contained in this document is error-free and Diodes is under no obligation to update or otherwise correct this information. Notwithstanding the foregoing, Diodes reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes.
- 8. Any unauthorized copying, modification, distribution, transmission, display or other use of this document (or any portion hereof) is prohibited. Diodes assumes no responsibility for any losses incurred by the customers or users or any third parties arising from any such unauthorized use.
- 9. This Notice may be periodically updated with the most recent version available at https://www.diodes.com/about/company/terms-and-conditions/important-notice

The Diodes logo is a registered trademark of Diodes Incorporated in the United States and other countries. All other trademarks are the property of their respective owners.

© 2025 Diodes Incorporated. All Rights Reserved.

www.diodes.com

MSB30L08 5 of 5 September 2025

Document number: DS45040 Rev. 3 - 2 www.diodes.com © 2025 Copyright Diodes Incorporated. All Rights Reserved.